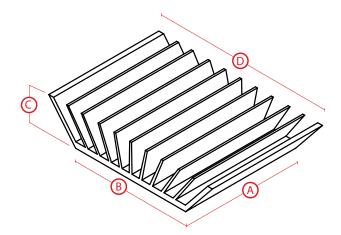


High Performance ASIC Cooling Solutions w/Thermal Tape Attachment

ATS PART # ATS-56008-C3-R0

Features & Benefits

- » maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » Designed specifically for ASIC package and their unique cooling requirements
- » Comes preassembled with high performance thermal interface material



*Image above is for illustration purposes only.



Thermal Performance

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AIR VELOCITY				THERMAL RESISTANCE		
	FT/MIN	MIN M/S		°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
	200 1.0		.0	2.1	1.3	
	300	1	.5	1.6		
	400		.0	1.3		
	500	2	.5	1.15		
	600	3	.0	1		
700 3.5		.5	0.84			
	800	4	.0	0.78		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
50 mm	45 mm	16 mm	69 mm	SAINT-GOBAIN C675	BLACK-ANODIZED

NOTES:

1) Dimension C = heat sink height from bottom of the base to the top of the fin field.

 Thermal performance data are provided for reference only. Actual performance may vary by application.

 ATS reserves the right to update or change its products without notice to improve the design or performance.

4) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).